



**Thyristor Module**

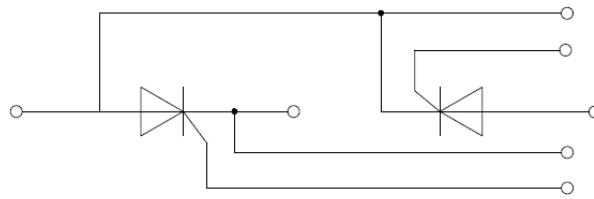
**Features**

- Half-bridge SCR configuration integrated In a single package
- High-thermal-conductivity DBC insulation for excellent heat dissipation
- Vacuum soldering technology for enhanced reliability

Parameter	Value	Unit
$V_{RRM}$	1600	V
$I_{T(AV)}$ (@ $T_C = 85^\circ C$ )	70	A
$I_{TSM}$ (@ $t_p = 10ms$ )	1400	A
$V_T(Max)$	1.80	V

**Applications**

- Heating control
- Light control system
- DC motor



**Absolute Maximum Ratings (@  $T_C = 25^\circ C$  unless otherwise specified)**

Parameter	Conditions	Symbol	Values	Unit
Repetitive peak off-state voltage	$T_{vj} = 25^\circ C$	$V_{DRM}$	1600	V
Repetitive peak reverse voltage	$T_{vj} = 25^\circ C$	$V_{RRM}$	1600	V
Non-repetitive peak off-state voltage	$T_{vj} = 25^\circ C$	$V_{DSM}$	1700	V
Non-repetitive peak reverse voltage	$T_{vj} = 25^\circ C$	$V_{RSM}$	1700	V
Average forward current	$T_C = 85^\circ C$	$I_{T(AV)}$	70	A
Forward surge current	1/2 cycle, Sine wave, 50Hz $T_{vj} = 25^\circ C$	$I_{TSM}$	1400	A
$I^2t$ value for fusing		$I^2t$	9800	A <sup>2</sup> s
Critical rate of rise of on-state current	$I_G=2 \times I_{GT}$	di/dt	150	A/ $\mu s$
RMS isolation voltage	A.C 50Hz(1s/1min)	$V_{ISO}$	3600/3000	V
Junction temperature range		$T_J$	-40 ~ +125	$^\circ C$
Storage temperature range		$T_{stg}$	-40 ~ +125	$^\circ C$

**Electrical Characteristics (@  $T_C = 25^\circ\text{C}$  unless otherwise specified)**

Parameter	Conditions	Symbol	Values			Unit
			Min.	Typ.	Max.	
Peak forward voltage	$I_T=210\text{A}$ , $t_P=380\mu\text{s}$	$V_T$			1.80	V
Repetitive peak off-state current	$V_D = V_{\text{DRM}}$ , $T_{vj} = 25^\circ\text{C}$	$I_{\text{DRM}}$			100	$\mu\text{A}$
	$V_D = V_{\text{DRM}}$ , $T_{vj} = 125^\circ\text{C}$				30	mA
Reverse leakage current	$V_R = V_{\text{RRM}}$ , $T_{vj} = 25^\circ\text{C}$	$I_{\text{RRM}}$			100	$\mu\text{A}$
	$V_R = V_{\text{RRM}}$ , $T_{vj} = 125^\circ\text{C}$				30	mA
Threshold voltage	For power loss calculation only $T_{vj} = 125^\circ\text{C}$	$V_{\text{TO}}$			0.92	V
Dynamic resistance	$T_{vj} = 125^\circ\text{C}$	$r_T$			3.3	$\text{m}\Omega$
Triggering gate current	$V_D=12\text{V}$ $R_L=30\Omega$	$I_{\text{GT}}$	20		120	mA
Holding current	$I_T=1\text{A}$	$I_H$			250	mA
Latching current	$I_G=1.2 I_{\text{GT}}$	$I_L$			300	mA
Critical rate of rise of voltage	$V_D=2/3V_{\text{DRM}}$ $T_{vj}=125^\circ\text{C}$ Gate Open	$dv/dt$	1000			$\text{V}/\mu\text{s}$
Triggering gate voltage	$V_D=12\text{V}$ $R_L=30\Omega$	$V_{\text{GT}}$			1.8	V
Non triggering gate voltage	$V_D=0.5V_{\text{DRM}}$ $T_{vj}=125^\circ\text{C}$	$V_{\text{GD}}$	0.25			V

**Thermal Characteristics (@  $T_C = 25^\circ\text{C}$  unless otherwise specified)**

Parameter	Conditions	Symbol	Values			Unit
			Min.	Typ.	Max.	
Thermal resistance, junction to case	per Thyristor	$R_{\text{th(j-c)}}$		0.35		$^\circ\text{C}/\text{W}$
Thermal resistance, case to heatsink	per Thyristor	$R_{\text{th(c-s)}}$		0.18		$^\circ\text{C}/\text{W}$
Mounting torque	Module and heatsink fixed torque M5	M	4.25		5.75	N·m
	Electrode connection torque M5		2.55		3.45	N·m



Ordering Information

Device	Marking	Package	Weight	Inner Box	Pre Carton
JMT70KT16T1	JMT70KT16T1	T1	100±5g/PCS	10 PCS	120 PCS

Typical Electrical & Thermal Characteristics

FIG.1: Power dissipation vs. on-state current (per thyristor or diode)  
 $P_{T(AV)}/P_{F(AV)}(W)$

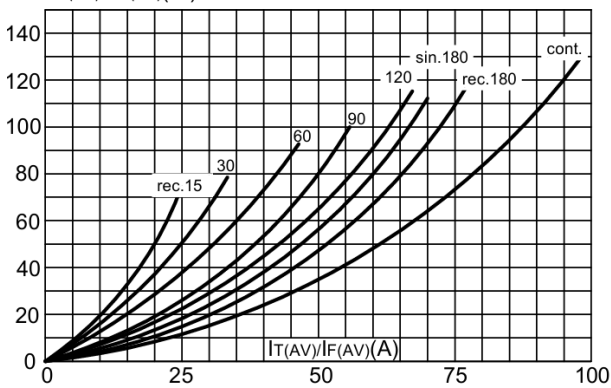


FIG.2: Maximum transient thermal impedance junction to case(per thyristor or diode)  
 $R_{th(j-c)}(^{\circ}C/W)$

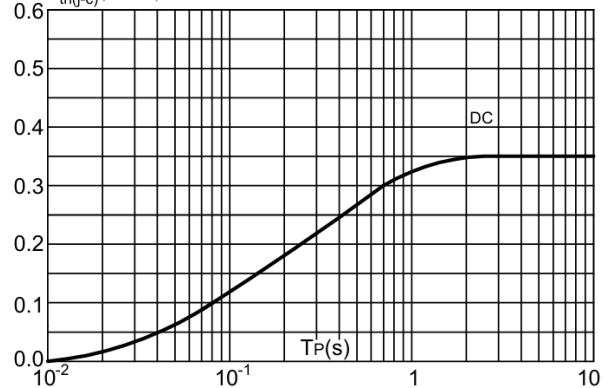


FIG.3: Forward characteristics (per thyristor or diode)  
 $I_F(A)/I_T(A)$

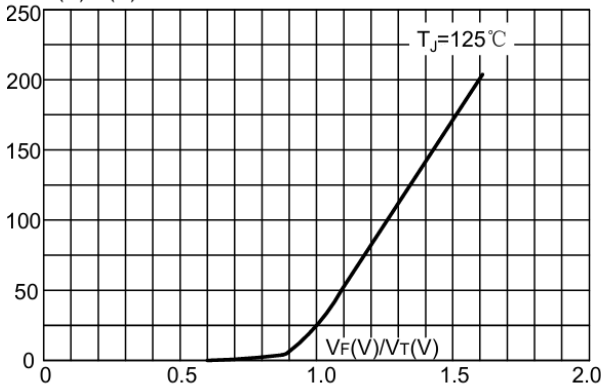
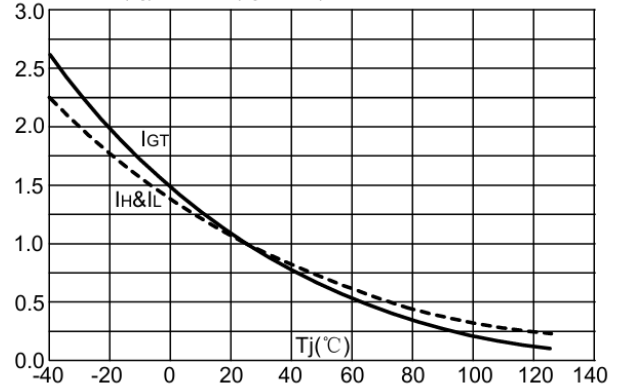
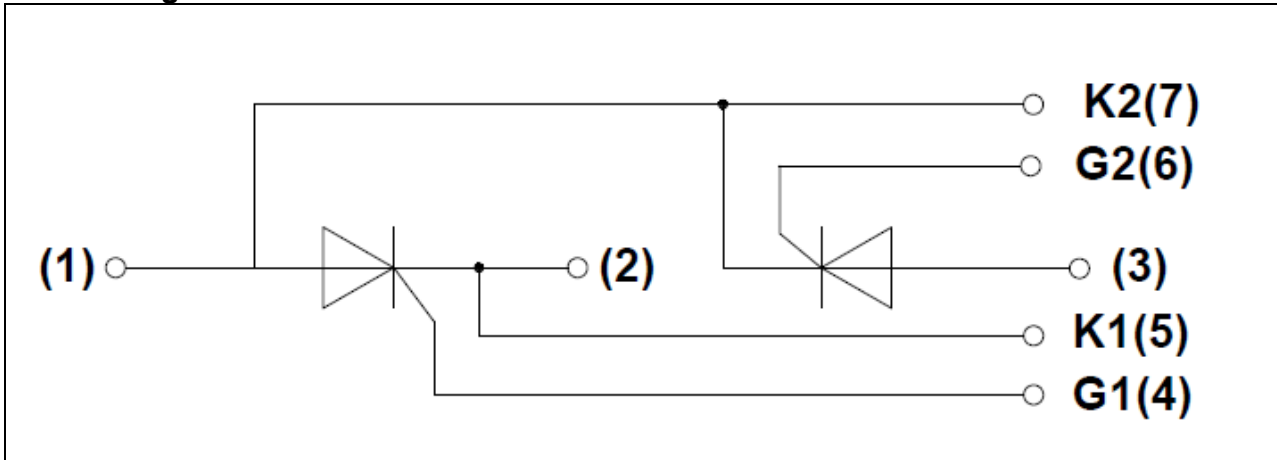


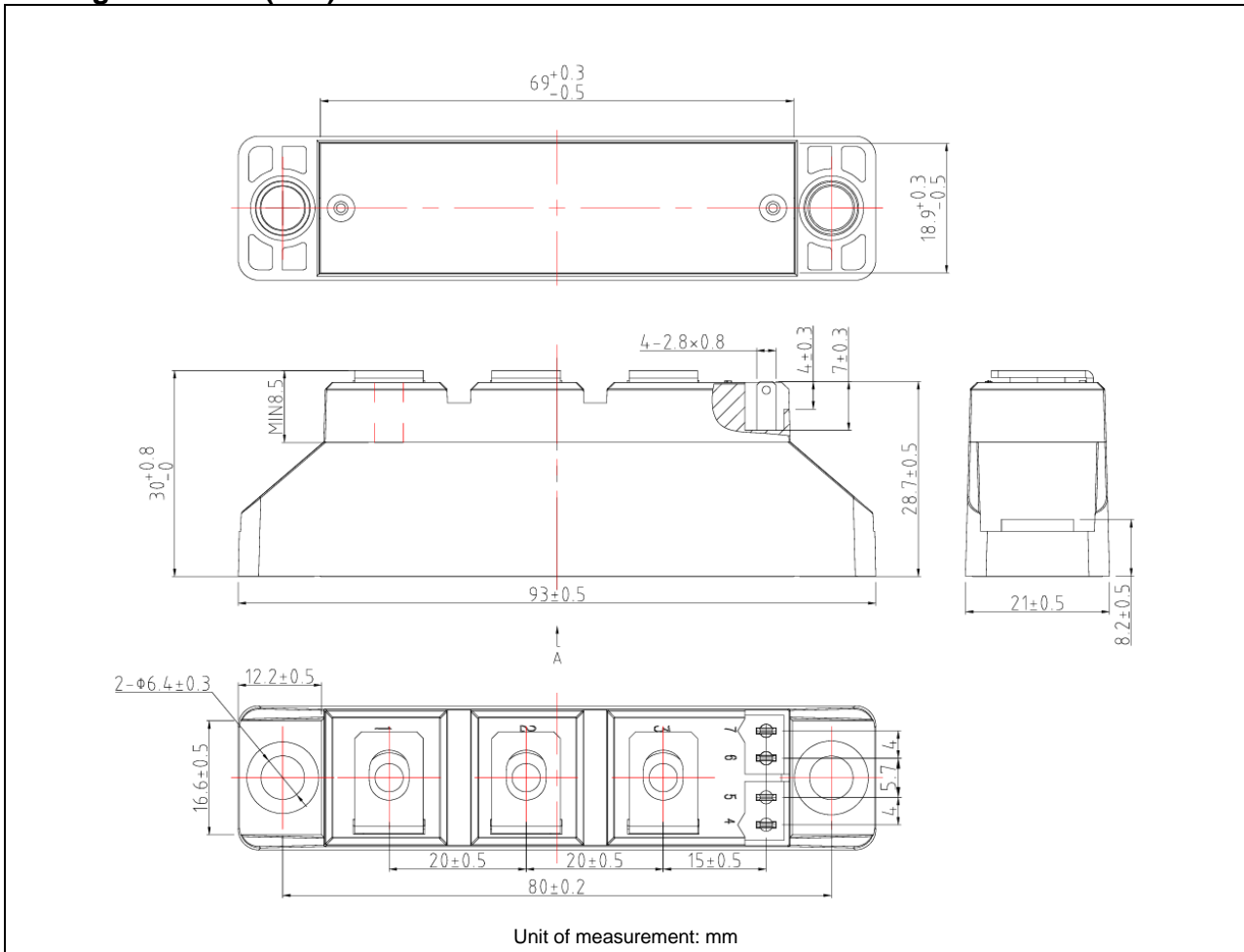
FIG.4: Relative variations of gate trigger current, holding current and latching current versus junction temperature  
 $I_{GT,IH,IL}(T_j)/I_{GT,IH,IL}(T_j=25^{\circ}C)$



**Circuit Diagram**




**Package Outlines (mm)**





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